



PRODUCT IDENTIFICATION

JRPI	1265	PV	- 3R3	M
Type	Size	Control	Inductance	
				Tol.

FEATURES

1. Shielded construction.
2. Capable of corresponding high frequency.
3. Low loss realized with low DCR.
4. High performance (Isat) realized by metal dust core.
5. Ultra low buzz noise, due to composite construction.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. High reliability -Reliability test complied to AEC-Q200
8. Operating temperature -55~+155°C
(Including self - temperature rise)

Marking and Date code:

Marking ex:3.3(μH) → 3R3

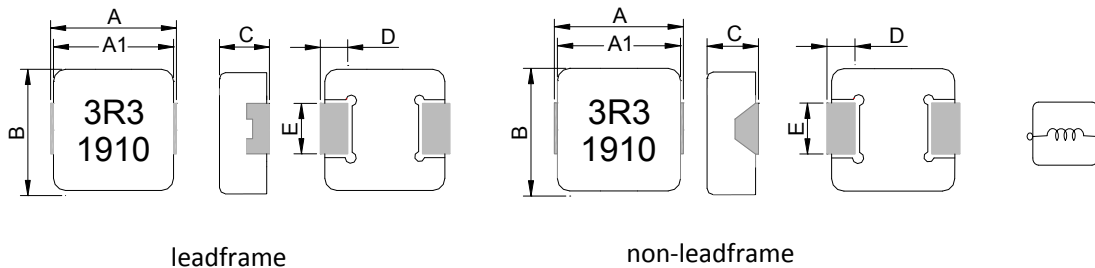
Date code

19 10 → year and weekly

APPLICATIONS

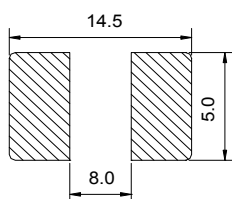
1. DC/DC converters in distributed power systems.
2. DC/DC converter for Field Programmable Gate Array(FPGA).
3. Battery powered devices.
4. Thin type on-board power supply module for exchanger.
5. VRM for server.
6. High current, low profile POL converters.
7. PDA/notebook/desktop/server and battery powered devices.

DIMENSIONS (mm)



印字:黑色3R3及D/C 1910 (19年,10週期)(依實際生產日期而定)

Recommend PC Board Pattern



Note:

1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

Part No.	Size (mm)					
	A	A1	B	C	D	E
JRPI 1265PV	13.5 ± 0.5	12.6 ± 0.3	12.6 ± 0.2	6.2 ± 0.3	2.3 ± 0.3	See Spec table

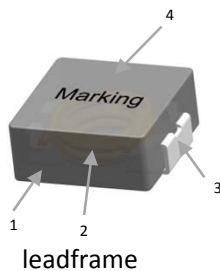
SERIES LIST

No.	Part No.	L (μ H) $\pm 20\%$	RDC (m Ω)		Isat (A)		Irms (A)		E (mm) ± 0.3	Type
			Typ.	Max.	Typ.	Max.	Typ.	Max.		
1	JRPI 1265PV-R10N	0.10 $\pm$ 30%	0.20	0.25	120	115	65	60	4.7	non-leadframe
2	JRPI 1265PV-R22M	0.22	0.40	0.46	112	105	53	42	4.7	non-leadframe
3	JRPI 1265PV-R68M	0.68	1.25	1.50	55	46	36.5	33	4.0	non-leadframe
4	JRPI 1265PV-1R0M	1.00	1.50	1.80	45	36	33	29	4.0	non-leadframe
5	JRPI 1265PV-1R5M	1.50	2.20	2.53	35	30	29	25	4.0	non-leadframe
6	JRPI 1265PV-2R2M	2.20	3.70	4.20	28.5	24	25	21	4.7	leadframe
7	JRPI 1265PV-3R3M	3.30	5.30	6.20	27	22.5	22	19	4.7	leadframe
8	JRPI 1265PV-4R7M	4.70	6.80	8.00	25	21	20	17	4.7	leadframe
9	JRPI 1265PV-5R6M	5.60	8.30	9.80	23	19.5	18	15	4.7	leadframe
10	JRPI 1265PV-6R8M	6.80	9.80	11.3	21	18	16.5	14	4.7	leadframe
11	JRPI 1265PV-8R2M	8.20	12.0	13.8	19	17	15	12.5	4.7	leadframe
12	JRPI 1265PV-100M	10.0	13.0	15.8	17	15	13	11	4.7	leadframe
13	JRPI 1265PV-220M	22.0	31.0	35.0	10	9	10	8	4.7	leadframe
14	JRPI 1265PV-330M	33.0	46.0	55.0	9	8	9	7	4.7	leadframe

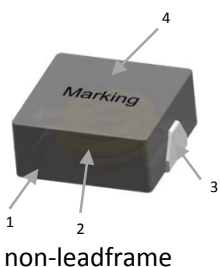
Note:

1. Test Frequency: 100KHz /1V
2. All test data referenced to 25 $^{\circ}$ C ambient
3. Saturation Current (Isat) will cause L0 to drop approximately 30%.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately Δ T of 40 $^{\circ}$ C
5. The part temperature (ambient + temp rise) should not exceed 155 $^{\circ}$ C under worst case operating conditions.
Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
6. Special inquiries besides the above common used types can be met on your requirement.

Materials

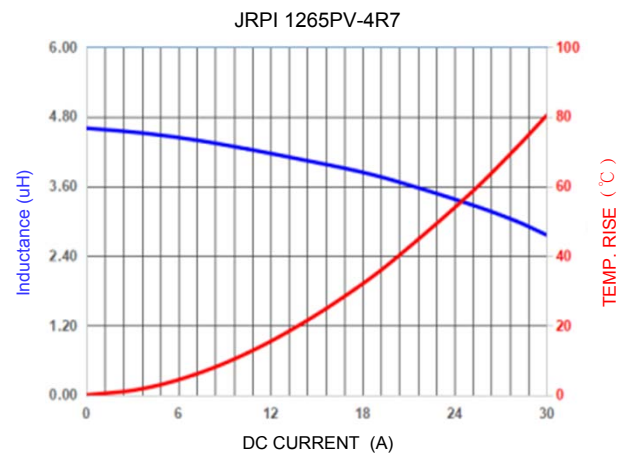
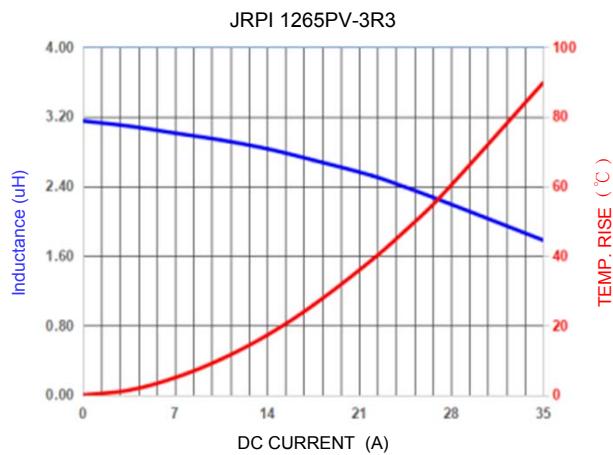
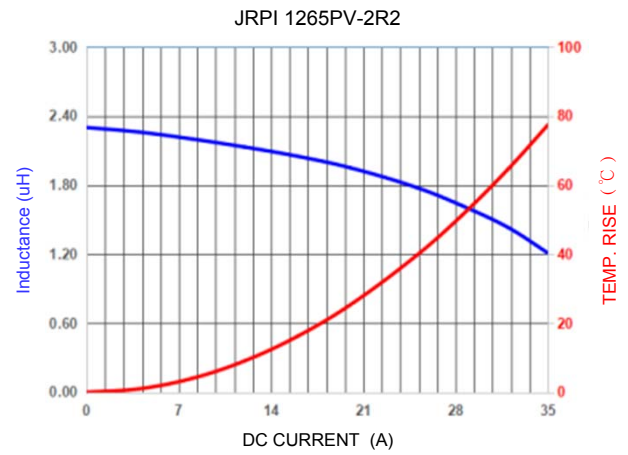
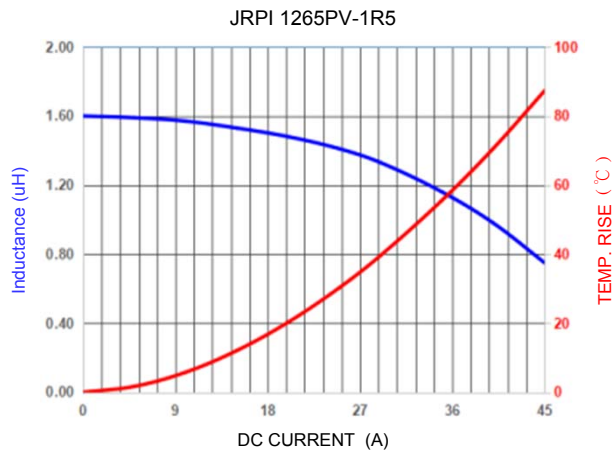
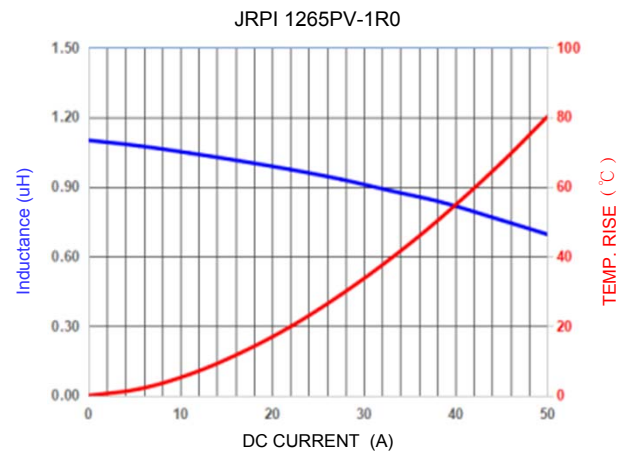
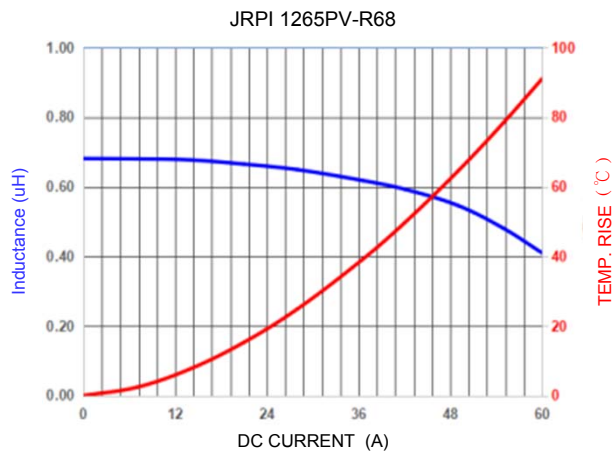
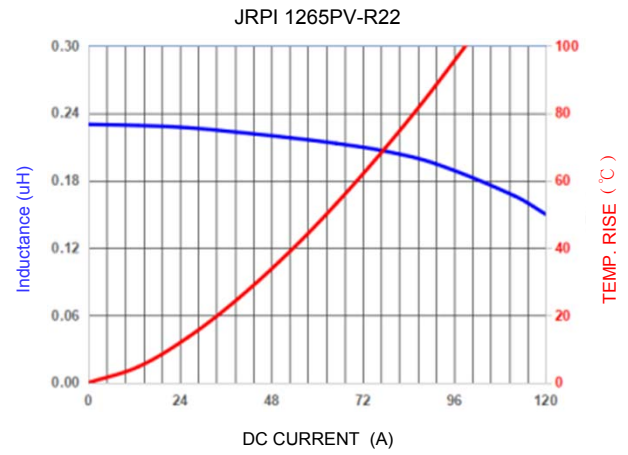
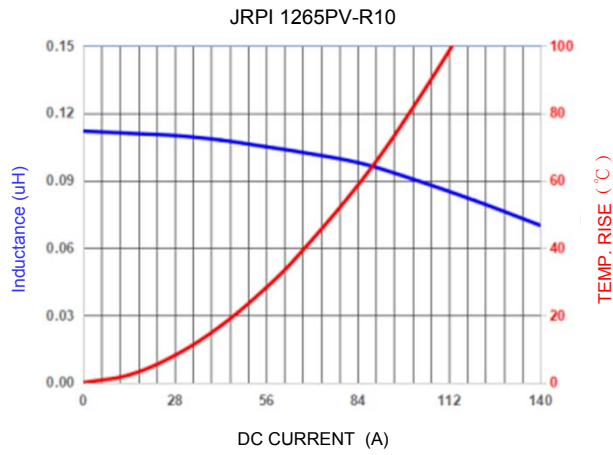


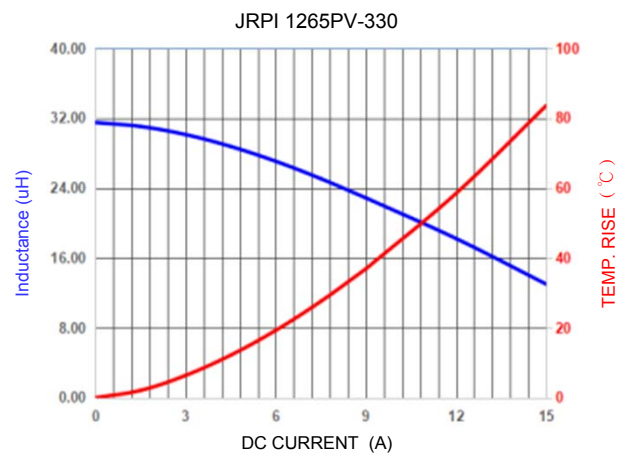
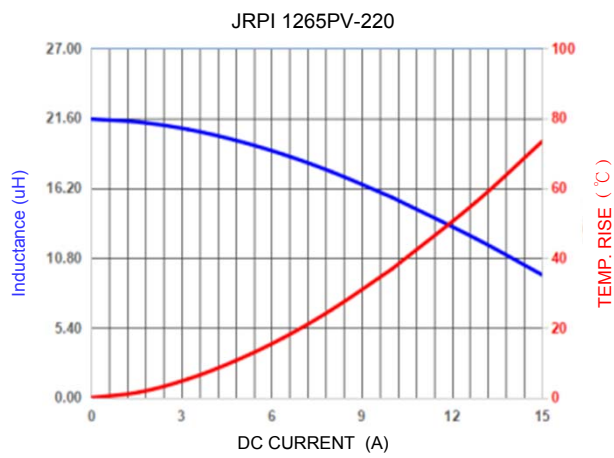
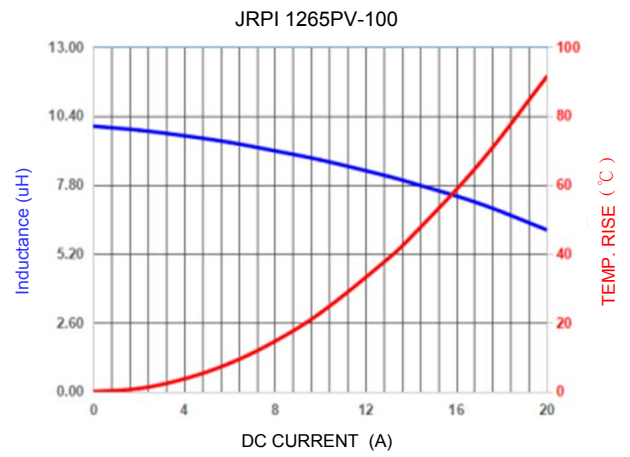
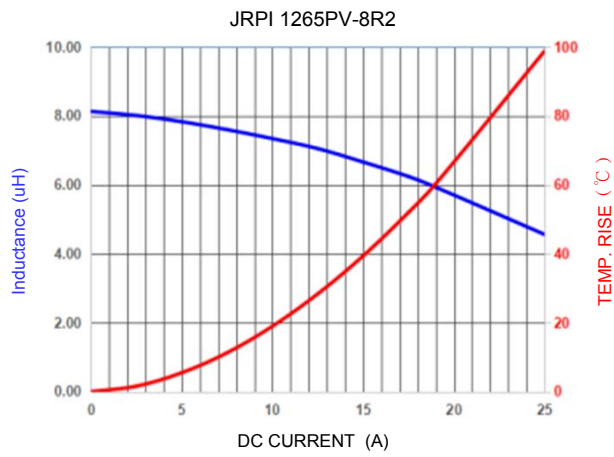
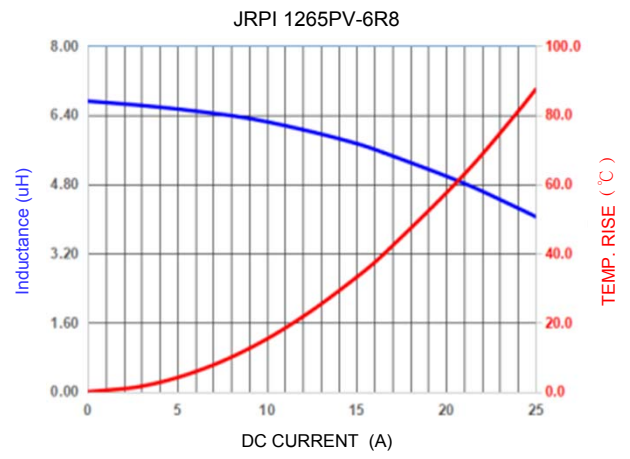
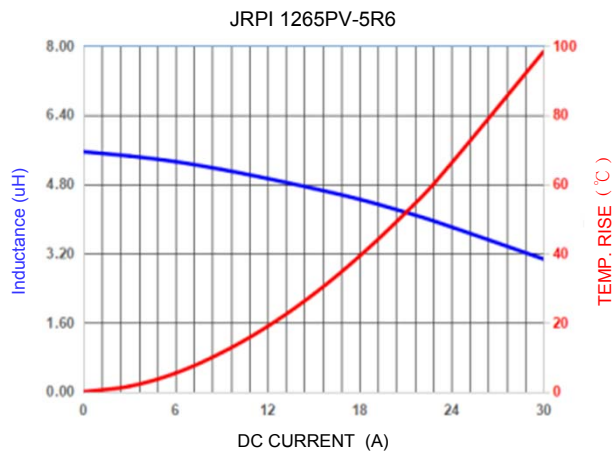
NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent.
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Ink	Halogen-free ketone



NO	Items	Materials
1	Core	Alloy Powder
2	Wire	Polyester Wire or equivalent.
3	Solder	100% Pb free solder
4	Ink	Halogen-free ketone

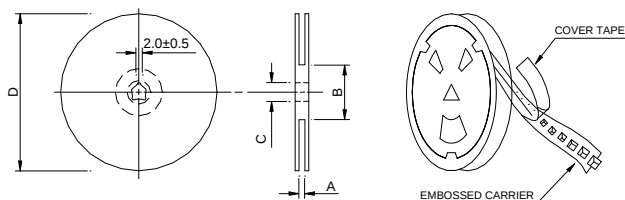
Typical Performance Curves





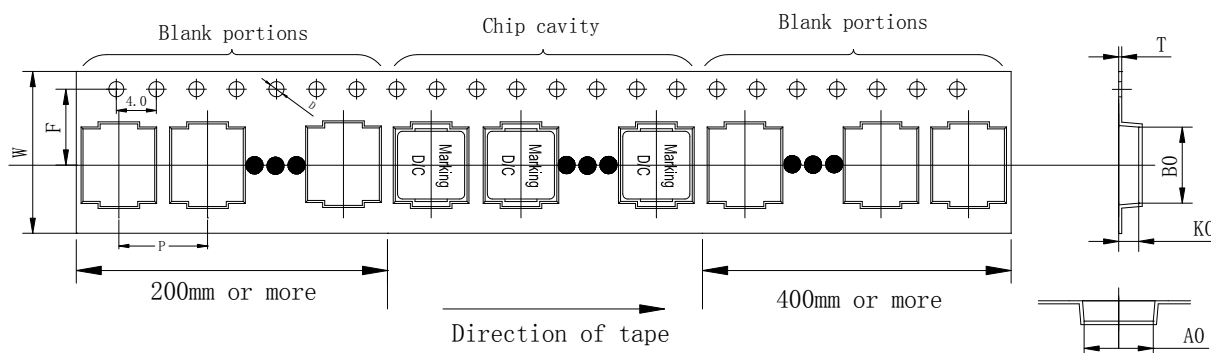
Packaging Information

• Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	$24.4 \pm 2/-0$	100 ± 2	$13 \pm 0.5/-0.2$	330

• Tape Dimension

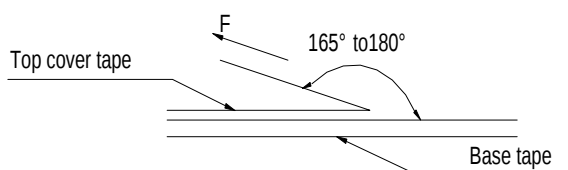


Ao(mm)	Bo(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)	D(mm)
12.9 ± 0.1	14.1 ± 0.1	7.0 ± 0.1	16 ± 0.1	24 ± 0.3	11.5 ± 0.1	0.35 ± 0.1	1.5 ± 0.1

• Packaging Quantity

Size	Reel	Inner box	Carton
JRPI 1265PV	500	1000	4000

• Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions (referenced ANSI/EIA-481-C-2003 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

■ Application Notice

- Storage Conditions(component level)

To maintain the solderability of terminal electrodes:

1. Products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
2. Temperature and humidity conditions: Less than 40°C and 60% RH.
3. Recommended products should be used within 12 months form the time of delivery.
4. The packaging material should be kept where no chlorine or sulfur exists in the air.

- Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.